

RECOMMENDED PCB LAYOUT  
(ALL TOLERANCE ARE ±0.05)

PAD AREA

Pin Define

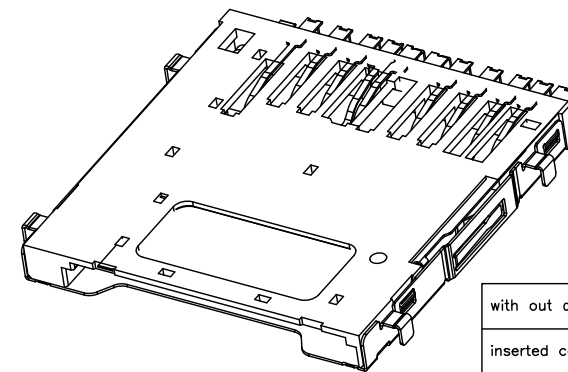
Connector Pin No.	SD Card Pin No.	Pin Define
P1	P9	DAT2
P2	P1	DAT3
P3	P2	CMD
P4		CD
P5	P3	VSS1
P6	P4	VDD
P7	P5	CLK
P8	P6	VSS2
P9	P7	DATO
P10	P8	DAT1
P11		W/P
P12		GND
P13		GND
P14		GND
P15		GND

NOTES :

- MATERIAL :
  - HOUSING:LCP UL94 S475 V-0, BLACK COLOR.
  - SHELL:STAINLESS STEEL SUS304 T=0.20mm.
  - CONTACT:COPPER ALLOY C5210 T=0.15mm.
- FINISH :
  - CONTACT: GOLD PLATING ON CONTACT AREA, MATTE TIN 80u"MIN ON SOLDER TAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
  - SHELL: 30U" MIN SOLDERABLE NICKEL PLATED OVER ALL.
- ELECTRICAL CHARACTERISTICS:
  - OPERATING VOLTAGE : 100V AC(rms)/DC.
  - CURRENT RATING : 0.5 A.
  - OPERATING TEMPERATURE: -25°C~+85°C.
  - CONTACT RESISTANCE: 100 m OHMS MAX.
  - INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
  - DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

PART.NO.:  
TW70-AP401-\*\*

- 功能区镀金10u", 锡脚镀雾纯锡至少80u"
- 功能区镀金30u", 锡脚镀雾纯锡至少80u"
- 功能区镀金50u", 锡脚镀雾纯锡至少80u"
- 功能区镀金100u", 锡脚镀雾纯锡至少80u"
- 功能区镀金150u", 锡脚镀雾纯锡至少80u"
- 功能区镀金300u", 锡脚镀雾纯锡至少80u"



with out card	C/D(P4) —○— VSS1(P5)
	W/P(P11) —○— GND(P12)
inserted card (unlock)	CD(P4) —○— VSS1(P5)
	W/P(P11) —○— GND(P12)
inserted card(lock)	CD(P4) —○— VSS1(P5)
	W/P(P11) —○— GND(P12)

GENERAL TOLERANCE		DWG.NO.	TW70-AP401-00	PART.NO.	TW70-AP401-**	DRAWN	L.M.J 2015.12.04	UNIT	mm	SCALE	1:1
x.±0.50	x. °±5 °	REV.	A	TITLE	SD Push H3.15 Sink 2.30 Conn.	CHECKED		东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x±0.25	.x °±2 °	SIZE		SHEET	1 OF 2	APPROVED					
.xx±0.15	.xx ±1 °	A4									